

Title (en)
CONNECTOR FOR HIGH-SPEED TRANSMISSION AND METHOD FOR FIXING SOLDER TO FORK PORTION OF CONNECTOR FOR HIGH-SPEED TRANSMISSION

Title (de)
VERBINDER FÜR HOCHGESCHWINDIGKEITSÜBERTRAGUNG UND VERFAHREN ZUR BEFESTIGUNG VON LÖTMITTEL AN EINEM GABELTEIL EINES VERBINDERS FÜR HOCHGESCHWINDIGKEITSÜBERTRAGUNG

Title (fr)
CONNECTEUR POUR TRANSMISSION À GRANDE VITESSE ET PROCÉDÉ DE FIXATION DE SOUDURE À LA PARTIE FOURCHE DU CONNECTEUR POUR TRANSMISSION À GRANDE VITESSE

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Application
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Abstract (en)
According to an embodiment of the present disclosure, a contact for high-speed transmission is provided. The contact (CNH, CNP) of the present embodiment includes a housing (1H, 1P) and a plurality of terminals (3H, 3P). The plurality of terminals (3H, 3P) have contact portions (37H, 37P) in contact with a counterpart connector (CNP, CNH) and soldering terminal portions soldered to a mounting target substrate (91, 90) in which the contact portions (37H, 37P) and the soldering terminal portions are arranged in the housing (1H, 1P) so as to face each other. The soldering terminal portion is a fork portion (30H, 30P), and a cut piece of a wire solder (300) is sandwiched and crimped in the fork portion (30H, 30P). The disclosed connector can reduce the overheating process of the terminal in the reflow and reduce the adverse effect on the finished product due to the heat treatment.

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Citation (applicant)
JP 2018156936 A 20181004 - MOLEX LLC

Citation (search report)

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